_____MOBILE RADIO

MAINTENANCE MANUAL

406—512 MHz RF ASSEMBLY 19D417075G9-G16 AND

IF FILTER BOARD 19C320523G2

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DESCRIPTION

The RF Assembly uses five tuned helical resonators to provide front end RF selectivity with no gain. A UHS pre-amplifier assembly is available that can be used with the receiver to improve sensitivity.

Mixer board A303 uses the RF signal from the RF Assembly and the mixer injection frequency from the oscillator multiplier board to generate the IF frequency.

CIRCUIT ANALYSIS

RF ASSEMBLY

PRE-AMPLIFIER

The pre-amplifier is present only in UHS receivers, and uses a bi-polar transistor to provide approximately 10 dB gain.

RF from the antenna is link-coupled through helical resonator L2301 to the base of Class A pre-amplifier Q2301. L2301 matches the 50-ohm input to the base of Q2301. The amplified output is coupled through L2302, and connected through W2301 to J1 on Antenna Input Board A301. P2301 connects to J502 on the IF-Filter Board for regulated +10-Volt supply voltage.

ANTENNA INPUT A301A/A301B

An RF signal from the antenna or UHS pre-amplifier is applied to A301 which provides an AC ground between vehicle ground

and receiver A-. Resistor R1 prevents a static charge from building up on the vehicle antenna. The output of A301 is coupled through five high Q helical resonators that provide the front end RF selectivity. The helicals are tuned to the incoming frequency by C301 through C305.

MIXER A303

The mixer uses a FET (Q1) as the active device. The FET mixer provides a high input impedance, high power gain, and an output relatively free of harmonics (low in intermodulation products).

In the mixer stage, RF from the helical resonators is coupled through L1 and C2 which matches the RF output to the gate of mixer Q501. Injection voltage from the multiplier-selectivity stages is applied to the source of the mixer. The 11.2 MHz mixer IF output signal is coupled from the drain of Q1 through cable W1 to J501 on the IF Filter board.

IF-FILTER

CRYSTAL FILTER

The output of A303-Ql is coupled through a tuned circuit (L507 and C515) which matches the output to the input of the four-pole monolithic crystal filter. The highly-selective crystal filter (FL501 and FL502) provides the first portion of the receiver IF selectivity. The output of the filter is coupled through impedance-matching network L503 and C511 to the IF amplifier.

Service Note: Variable capacitor C504 does not require adjustment when performing normal alignment. If the four-pole monolithic crystal filter is replaced, then adjustment of C504 is necessary for optimum IF response.

IF AMPLIFIER

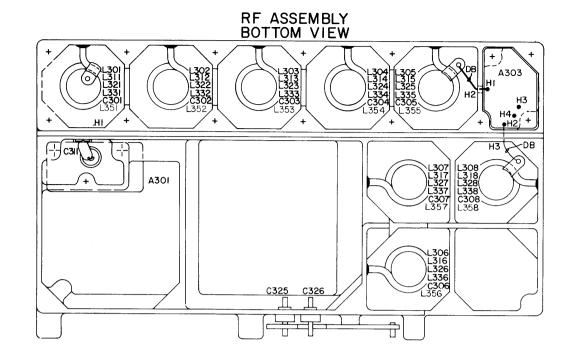
IF Amplifier Q501 is a dual-gate FET. The filter output is applied to Gate 1 of the amplifier, and the output is taken from

the drain. The biasing on Gate 2 and the drain load determines the gain of the stage. The amplifier provides approximately 20 dB of IF gain. The output of Q501 is coupled through a network (L504 and C509) that matches the amplifier output to the crystal filter on the IFAS board. The output of the IF-Filter board is applied to the IFAS board through feed-through capacitor C325.

Supply voltage for the RF amplifier and IF-Filter board is supplied from the IFAS board through feed-through capacitor C326.

MOBILE RADIO DEPARTMENT
GENERAL ELECTRIC COMPANY • LYNCHBURG, VIRGINIA 24502



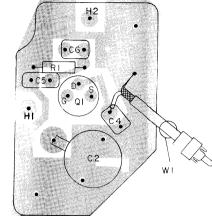


A30IB

ANT INPUT

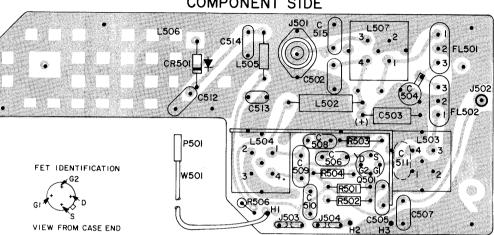
(NON- FLOATING GROUND)

MIXER A304

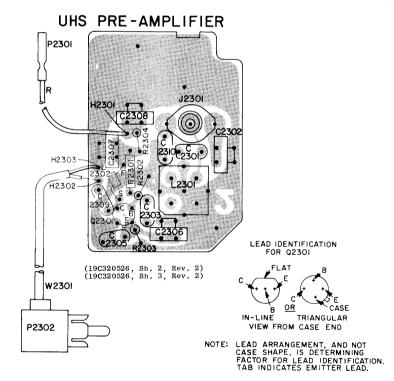


(19D429194, Sh. 2, Rev. 1) (19D429194, Sh. 3, Rev. 1)

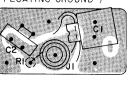
IF-FILTER BOARD COMPONENT SIDE



(19C320522, Sh. 2, Rev. 6) (19C320522, Sh. 3, Rev. 6)







(19B219941, Sh. 2, Rev. 0) (19B219941, Sh. 3, Rev. 0)

LEAD IDENTIFICATION FOR QI

TRIANGULAR
VIEW FROM CASE END

NOTE LEAD ARRANGEMENT, AND NOT CASE SHAPE, IS DETERMINING FACTOR FOR LEAD DENTIFICATION. TAB INDICATES EMITTER LEAD.

SOLDER SIDE | Color |

RUNS ON SOLDER SIDE

RUNS ON BOTH SIDES

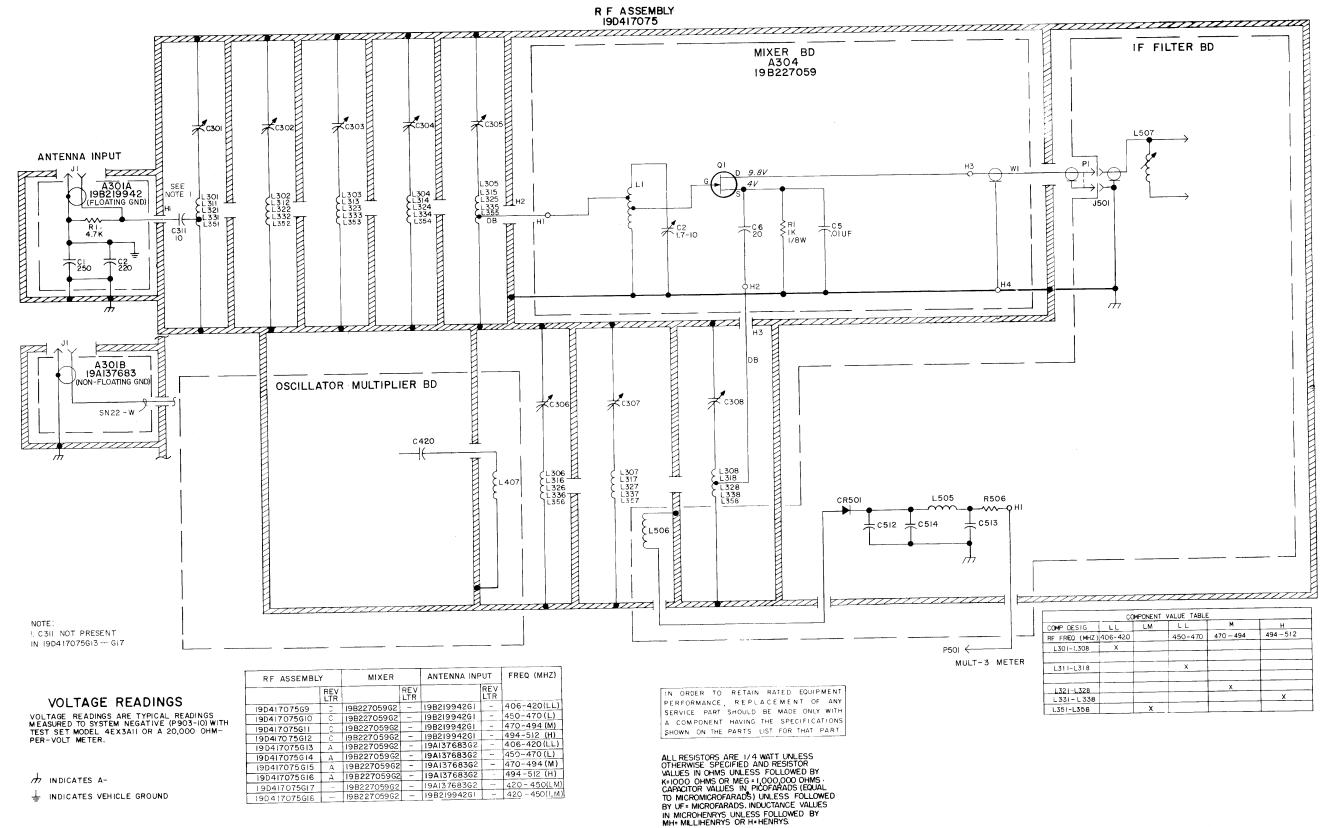
RUNS ON COMPONENT SIDE

OUTLINE DIAGRAM

406-512 MHz RF ASSEMBLY BOARD 19D417075G9-G16 AND IF FILTER BOARD 19C320523G2

(19D423794, Rev. 5)

Issue 5

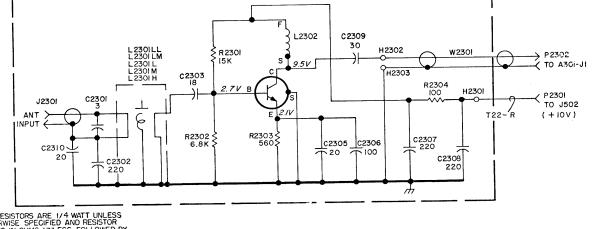


(19D423520, Rev. 7)

SCHEMATIC DIAGRAM

406—512 MHZ RF ASSEMBLY BOARD 19D417075G9-G16

Issue 5



UHS PRE - AMPLIFIER

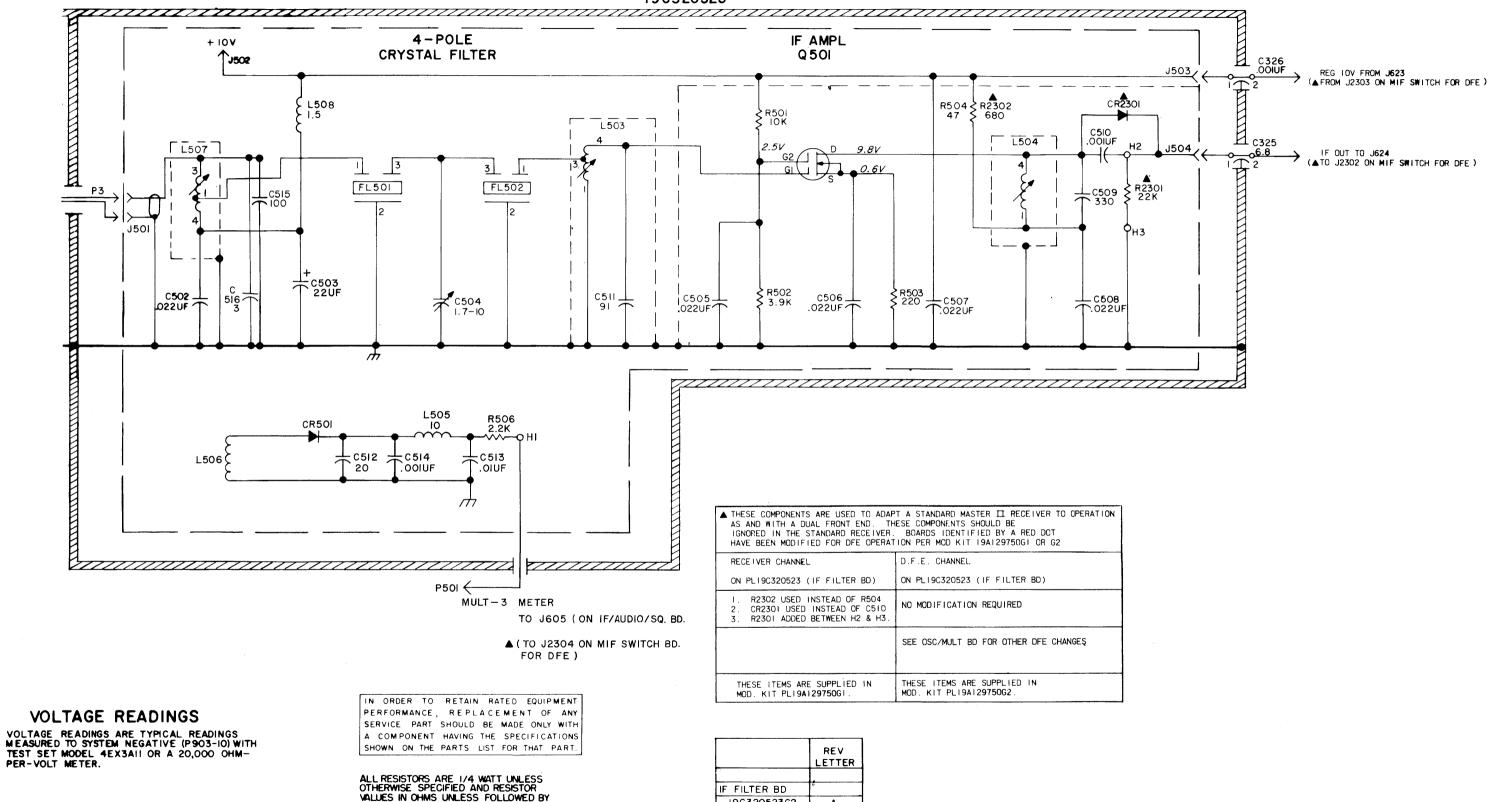
PRE AMPL Q2301

ALL RESISTORS ARE 1/4 WATT UNLESS OTHERWISE SPECIFIED AND RESISTOR VALUES IN OHMS UNLESS FOLLOWED BY K-1000 OHMS OF MEG-1,000,000 OHMS OCAPACITOR VALUES IN PICOFARADS (EQUAL TO MICROMICROFARADS) UNLESS FOLLOWED BY UF- MICROFARADS, INDUCTANCE VALUES IN MICROHENRYS UNLESS FOLLOWED BY MH- MIL LIFENRYS OR H-1ERRYS

IN ORDER TO RETAIN RATED EQUIPMENT PERFORMANCE, REPLACEMENT OF ANY SERVICE PART SHOULD BE MADE ONLY WITH A COMPONENT HAVING THE SPECIFICATIONS SHOWN ON THE PARTS LIST FOR THAT PART.

(19B226008, Rev. 5)

IF FILTER BD 190320523



INDICATES A-

INDICATES VEHICLE GROUND

19C32O523G2

SCHEMATIC DIAGRAM

IF FILTER BOARD 19C320523G2

VALUES IN OHMS UNLESS FOLLOWED BY
K=1000 OHMS OR MEG =1,000,000 OHMS
CAPACITOR VALUES IN PICOFARADS (EQUAL
TO MICROMICROFARADS) UNLESS FOLLOWED
BY UF = MICROFARADS. INDUCTANCE VALUES
IN MICROHENRYS UNLESS FOLLOWED BY
MH= MILLIHENRYS OR H=HENRYS.

LBI30032

PARTS LIST

LBI30033E

406-512 MHz RECEIVER RF ASSEMBLY, IF-FILTER BOARD ASSEMBLY AND UHS PRE-AMPLIFIER

SYMBOL	GE PART NO.	DESCRIPTION
		RF ASSEMBLY 19D417075G9 406-420 MHz 19D417075G10 420-470 MHz 19D417075G13 406-420 MHz 19D417075G14 420-470 MHz 19D417075G16 494-512 MHz 19D417075G16 494-512 MHz 19D417075G16 494-512 MHz
A301A		ANTENNA INPUT BOARD 19B219942G1
C1	7484398P3	Silver mica: 250 pf ±10%, 500 VDCW; sim to Underwood Type JlHF.
C2	19A116679P220K	Mica: 220 pf ±10%, 259 WDCW.
		JACKS AND RECEPTACLES
J1	7104941P16	Connector, phono: Jack; sim to National Tel. Barrel Ceramic.
		RESISTORS
R1	3R152P472J	Composition: 4.7K ohms ±5%, 1/4 w.
A301B*		ANTENNA INPUT PLATE 19A137683G2 (Added to G13-G16 by REV A)
		JACKS AND RECEPTACLES
Jl	7104941P20	Connector, jack: sim to National Tel.
A301B*		ANTENNA INDUT PLATE 19A137683G1 (Deleted in G13-G16 by REV A)
		JACKS AND RECEPTACLES
Jl	7104941P20	Connector, jack: sim to National Tel.
		RESISTORS
R1	3R152P472J	Composition: 4.7K ohms ±5%, 1/4 w.
A303*		MIXER BOARD 19B227059G1 (Deleted by REV B)
		CAPACITORS
C1	19A116080P103	Polyester: 0.022 μf ±10%, 50 VDCW.
C2	19B209351P1	Variable, ceramic: 2-10 pf, 200 VDCW, temp coef -350 +500 PPM/°C; sim to Matshushita ECV-1ZW10P3:
C3	19A116656P20K0	Ceramic disc: 20 pf ±10%, 500 VDCW, temp coef 0 PPM.
C4*	19A116114P12	Ceramic: 3.3 pf ±5%, 103 VDCW; temp coef 0 PPM.
	19A116656P3K0	Earlier than REV A: Ceramic disc: 3 pf ±1 pf, 500 VDCW, temp coef
	10	O PPM.
		INDUCTORS
Ll		(Part of printed wiring board 19D423518P1).
		(Part of W1)
Pl.		(Part of W1).

SYMBOL	GE PART NO.	DESCRIPTION	SYMBO
		RESISTORS	L325
R1	3R151P102K	Composition: 1K ohms ±10%, 1/8 w.	L326 and
			L327
W1	5491689P114	RF: approx 5-1/8 inches long.	L328 L331
A304*		MIXER BOARD 19B227059G2 (Added by REV B)	L332 thru L334
		CAPACITORS	L335
C2	19B209351P1	Variable, ceramic: 2-10 pf, 200 VDCW, temp coef -350 +500 PPM/°C; sim to Matshushita ECV-1ZW10P32.	L336 and L337
C4*	19All6ll4Pl2	Ceramic: 3.3 pf ±5%, 100 VDCW; temp coef 0 PPM.	L338
C5	19A116192P1	Deleted in G9-G12 by REV C, in G13-G16 by REV A. Ceramic: 0.01 µf ±20%, 50 VDCW; sim to Erie	
		8121 SPECIAL. Ceramic: 20 pf ±5%, 100 VDCW; temp coef 0 PPM.	l
C6	19A116114P39		
.,			C502
Ll			
P1		(Part of W1).	C504
PI			C505 thru
Q1	19A134093P1	N Type, field effect; sim to Type 2N4391.	C508 C509
4,1		RESISTORS	C510
R1	3R151P102K	Composition: 1K ohms ±10%, 1/8 w.	İ
		CABLES	C511 C512
W1	5491689P114	Cable, RF: approx 5-1/2 inches long.	
1			C513
C301		Includes:	i i
thru C305	4036765G11	Screw.	C515
	7137968P8	Nut, stamped: thd size No. 6-32; sim to Palnut T0632005.	C516*
C306 thru		Includes:	
C308	4036765G12 7137968P8	Nut, stamped: thd size No. 6-32; sim to Palnut	CR501
		T0632005.	
C311*	5496218P241	Ceramic disc: 10 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM. Deleted in Gl3-Gl6 by REV A.	FL501
C325	19B209488P1	Ceramic, feed-thru: 6.8 pf $\pm 20\%$, 500 VDCW; sim to Allen-Bradley Style FA5D.	FL502
C326	19B209488P2	Ceramic, feed-thru: 1000 pf +100%-10%, 500 VDCW; sim to Allen-Bradley Style FA5D.	12002
			J501
L301	19B204938G37	Coil.	J502
L302 thru L304	19B219944P1	Coil.	J503 and J504
L305	19B204938G33	Coil.	
L306 and	19B219944P5	Coil.	L502*
L307 L308	19B204938G41	Coil.	L503
L311	19B204938G38	Coil.	L504
L312 thru	19B219944P2	Coil.	1504
L314 L315	19B204938G34	Coil.	L505
L316	19B2049338G34 19B219944P6	Coil.	L506
and L317			L507
L318	19B204938G42	Coil.	L508*
L321 L322	19B204938G39 19B219944P3	Coil.	
thru L324			P501
1	1	1	1 1

DESCRIPTION	SYMBOL
Coil.	
Coil.	Q501
Coil.	R501
Coil.	R502
Coil.	R502
	R504
Coil.	R506
Coil.	
Coil.	W501
IF FILTER BOARD 19C320523G2	
Polyester: 0.022 μf ±10%, 50 VDCW.	
Tantalum: 22 μ f $\pm 20\%$, 15 VDCW; sim to Sprague Type 150D.	
Variable: 2 to 10 pf, 200 VDCW, temp coef +500% -350 PPM; sim to Matshushita ECV-1ZW10P32.	C2301
Polyester: 0.022 µf ±20%, 50 VDCW.	C2302
Silver mica: 330 p. ±10%, 500 VDCW; sim to	C2303
Electro Motive Type DM-15. Ceramic disc: 1000 pf ±20%, 1000 VDCW;	C2305
sim to RMC Type JF Discap. (Part of L503).	C2306
Ceramic disc: 20 pf ±10%, 500 VDCW, temp coef	C2307 and C2308
O PPM. Polyester: 0.01 µf ±10%, 50 VDCW.	C2309
Ceramic disc: 1000 pf ±10%, 1000 VDCW; sim to RMC Type JF Discap.	C2310
Silver mica: 100 pf ±5%, 500 VDCw; sim to Electro Motive Type DM-15.	
Ceramic disc: 3 pf ±1 pf, 500 VDCW, temp coef 0 PPM. Added by REV A.	J2301
DIODES AND RECTIFIERS	
Diode, hot carrier: Fwd. drop .350 volts max.	L2301LL
FILTERS	L2301L
Crystal, freq:	L2301M
Resonator A: 11,200000 KHz, Resonator B: 11,196024 KHz.	L2301H
(Part of FL501).	L2301LM
JACKS AND RECEPTACLES	1 12302
Receptacle, coaxial: sim to Cinch 14H11613.	
Contact, electrical: sim to Bead Chain L93-4.	P2301 P2302
Receptacle, wire spring.	P2302
INDUCTORS	Q2301
Choke, RF: 27.0 µh ±10%, 1.40 ohms DC res max; sim to Jeffers 4422-9K. Deleted by REV A.	
Coil. Includes:	R2301
Tuning slug.	R2302
Coil. Includes:	R2303
Tuning slug.	R2304
Coil, RF: 10.0 μh $\pm 10\%$, 3.10 ohms DC res max; sim to Jeffers 4446-4K.	
(Part of printed board 19C320522Pl).	W2301

Choke, RF: 1.50 µh ±10%, 0.28 ohms DC res max; sim to Jeffers 4412-7K. Added by REV A.

(Part of W501).

GE PART NO.

19B204938G35

19B219944P7

19B204938G43 19B204938G40

19B219944P4

19B204938G36 19B219944P3

19B204938G44

19A116080P103

5496267P10

19B209351Pl

19A116080P3

5490008P139

19A116655P19

19A116656P20K0

19A116080P101

19A116655P20

5490008P27

19A116656P3K0

19Al16052Pl

19B219573G7

19A130924G1

19A116975Pl

4033513Pl

7488079P48

19C320141G4

5493185P9

5493185P9 19B209420P125

19C320141G29

19C321810G1

7488079P34

SYMBOL	GE PART NO.	DESCRIPTION)L
		TRANSFERENCE	
		TRANSISTORS	
Q501	19A116818P1	N Channel, field effect.	
		RESISTORS	
R501	3R152P103K	Composition: 10K ohms ±10%, 1/4 w.	
R502	3R152P392J	Composition: 3.9K ohms ±5%, 1/4 w.	
R503	3R152P221J	Composition: 220 ohms ±5%, 1/4 w.	
R504	3R152P470J	Composition: 47 ohms ±5%, 1/4 w.	
R506	3R152P222K	Composition: 2.2K ohms ±10%, 1/4 w.	
		1	
W501	19A129947G7	Cable: orange, No. 22 stranded, approx 7-1/2 inches, includes (P501).	
		UHS RF PRE-AMPLIFIER 19C320527G1 406-420 MHz (LL)	
		19C320527G1 406-420 MHz (L) 19C320527G2 450-470 MHz (L) 19C320527G3 470-494 MHz (M)	
		19C320527G4 494-512 MHz (H)	
		19C320527G5 420-450 MHz (LM)	
C2301	19A116656P3J8	Ceramic disc: 3 pf ±0.1 pf, 500 VDCW, temp coef	

Mica: 220 pf ±10%, 250 VDCW.

Mica: 100 pf \pm 10%, 250 VDCW.

Mica: 220 pf ±10%, 250 VDCW.

Helical resonator.

Helical resonator.

Helical resonator.

Helical resonator.

(Part of W2301).

Silicon, NPN.

Ceramic disc: 18 pf ±5%, 500 VDCW, temp coef

Ceramic disc: 20 pf ±10%, 500 VDCW, temp coef

Ceramic disc: 30 pf pf ±5%, 500 VDCW, temp coef

Ceramic disc: 20 pf ±10%, 500 VDCW, temp coef

- - - - - - JACKS AND RECEPTACLES - - - - -Receptacle, coaxial: sim to Cinch 14H11613.

_ _ _ _ _ _ PLUGS _ _ _ _ _ _

_ _ _ _ _ _ _ TRANSISTORS - - - - - -

RF: approx 3 inches long. Includes P2302.

Contact, electrical: sim to Amp 42827-2.

Composition: 15K ohms ±5%, 1/4 w.

Composition: 6.8K ohms $\pm 10\%$, 1/4 w.

Composition: 560 ohms ±10%, 1/4 w.

Composition: 100 ohms $\pm 10\%$, 1/4 w.

19A116679P220K

19A116656P18J8

19A116656P20K0

19A116679P100K

19A116679P220K

19A116656P30J8

19A130924G1

19D413078G3

19D413078G5 19D413078G6

19D413078G7

19D413078G9

19A129716G4

4029840P2

19A116859P2

3R152P153J

3R152P682K

3R152P561K

3R152P101K

5491689P94

	SYMBOL	GE PART NO.		
		19E501121G1		
		19B227101G1		
		19B209209P306		
		4036765Gll		
		4036765G12		
		19B209209P306		

19B209209P306	Tap screw, Phillips Pozidriv $^{\oplus}$: No. 6-32 x 3/8. (Secures RF Circuit Cover).
4036765G11	Screw. (Part of C301-C305).
4036765G12	Screw. (Part of C306-C308).
7137968P8	Nut, stamped: thd size No. 6-32; sim to Palnut T0632005. (Part of C301-C308).
4031594P1	Insulator. (Used with C504 on IF Filter Board).
19B219470P2	Shield. (Used with IF Filter Board).

Casting, RF Circuit.

Cover, RF Circuit.

Can. (Used with L401-L403, L501, L503, L504). Can. (Used with L2301). A127060P2

DESCRIPTION

Washer, fiber. (Used with FL501, FL502). 5306P59

Washer, fiber. (Used with J501, J2301).

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after all the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A - RF Assembly 19D417075G9-12

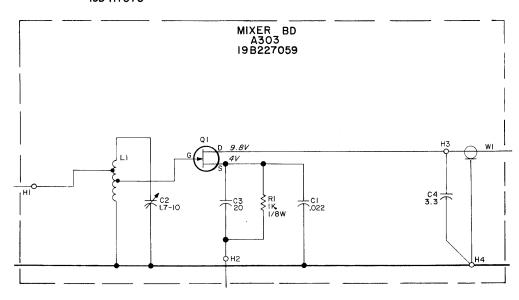
To improve receiver sensitivity. Changed C4.

REV. B - RF Assembly 19D417075G9-12

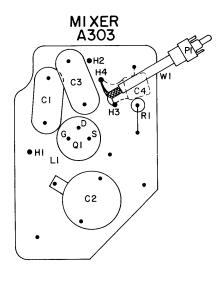
To incorporate new mixer board. Replaced A303 (19B227059Gl) with A304 (19B227059G2).

Schematic Diagram Was:

R F ASSEMBLY 19D417075



Outline Diagram Was:



REV. A - IF-Filter Board 19C320523G2

To improve operation. Replaced L502 with L508, and added C516.

REV. A - RF Assembly 19D417075G13-G16

REV. C - RF Assembly 19D417075G9-G12

To improve sensitivity. Deleted A304-C4.

*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES